

Serguei Stoukatch

List of Publications by Year in descending order

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Version: 2024-02-01

20
papers

405
citations

1163117

8
h-index

996975

15
g-index

20
all docs

20
docs citations

20
times ranked

401
citing authors

#	ARTICLE	IF	CITATIONS
1	A Miniaturized and Ultra-Low-Power Tamper Detection Sensor for Portable Applications. IEEE Sensors Journal, 2022, 22, 4524-4533.	4.7	0
2	Low Thermal Conductivity Adhesive as a Key Enabler for Compact, Low-Cost Packaging for Metal-Oxide Gas Sensors. IEEE Access, 2022, 10, 19242-19253.	4.2	4
3	Low-cost microfluidic device micromachining and sequential integration with SAW sensor intended for biomedical applications. Sensors and Actuators A: Physical, 2021, 319, 112526.	4.1	11
4	Preparation and Characterization of a Thermal Insulating Carbon Xerogel-Epoxy Composite Adhesive for Electronics Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 606-615.	2.5	7
5	Towards a Hybrid Mass Sensing System by Combining a QCM Mass Sensor With a 3-DOF Mode Localized Coupled Resonator Stiffness Sensor. IEEE Sensors Journal, 2021, 21, 8988-8997.	4.7	4
6	Fine pitch features laser direct patterning on flexible printed circuit board. Optics and Lasers in Engineering, 2020, 126, 105869.	3.8	10
7	Direct laser writing to fabricate capacitively transduced resonating sensor. Microsystem Technologies, 2020, 26, 547-562.	2.0	2
8	Anisotropic conductive film & flip-chip bonding for low-cost sensor prototyping on rigid & flex PCB. , 2020, , .		1
9	An Autonomous Sigfox Wireless Sensor Node for Environmental Monitoring. , 2019, 3, 01-04.		52
10	A Novel Qcm Mass Sensing System Incorporated with A 3-Dof Mode Localized Coupled Resonator Stiffness Sensor. , 2019, , .		3
11	355nm UV laser patterning and post-processing of FR4 PCB for fine pitch components integration. Optics and Lasers in Engineering, 2018, 100, 186-194.	3.8	9
12	Electrical characterization of Aerosol Jet Printing (AJP) deposited conductive silver tracks on organic materials. Microelectronic Engineering, 2018, 197, 67-75.	2.4	12
13	A mass sensor based on 3-DOF mode localized coupled resonator under atmospheric pressure. Sensors and Actuators A: Physical, 2018, 279, 254-262.	4.1	42
14	Autonomous micro-platform for multisensors with an advanced power management unit (PMU). Journal of Sensors and Sensor Systems, 2018, 7, 299-308.	0.9	5
15	Wicking through a confined micropillar array. Microfluidics and Nanofluidics, 2016, 20, 1.	2.2	16
16	Droplet formation by squeezing in a microfluidic cross-junction. Microfluidics and Nanofluidics, 2016, 20, 1.	2.2	47
17	Analysis of the Induced Stresses in Silicon During Thermcompression Cu-Cu Bonding of Cu-Through-Vias in 3D-SiC Architecture. , 2007, , .		40
18	Mechanical reliability of Au and Cu wire bonds to Al, Ni/Au and Ni/Pd/Au capped Cu bond pads. Microelectronics Reliability, 2006, 46, 1315-1325.	1.7	91

#	ARTICLE	IF	CITATIONS
19	The influence of packaging materials on RF performance. Microelectronics Reliability, 2003, 43, 351-357.	1.7	10
20	Direct gold and copper wires bonding on copper. Microelectronics Reliability, 2003, 43, 913-923.	1.7	39